

*Filed Via Facsimile*PATENT APPLICATION
Docket No. 11675.184.1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Salman Akram

Serial No.

10/033,233

Filed:

December 28, 2001

For:

CHIP PACKAGE WITH GREASE HEAT SINK
AND METHOD OF MAKING

Confirmation No.:

9685

Examiner:

Khiem D. Nguyen

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Art Unit
2823AMENDMENT AND RESPONSEMail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Advisory Action dated November 19, 2004, please enter the following amendments and remarks into the file of the above-identified application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.